IPC ASSOCIATION CONNECTION ELECTRONICS INDUSTRI	Material Composi © Copyright 2005. IPC, international and Pan-Ai	Bannockb	urn, Illinois. A	all rights reserved un	This d level p	locument i	is a declara declaration	ation of the s	ubstance: es all low	s within the manufactur er level materials for wl	er listed hich the 1	item. Note: if manufacturer	the item is an as has engineering	ssembly with low responsibility.	
752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Form Type Distribute				Form Type * Distribute		Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi					ials and Mfg Information			
upplier Inforn	nation														
Company name*			Company unique ID			Unio	Unique ID Authority					Response Date*			
nsemi												2024-05-02			
Contact Name			Title - Contact			Pho	Phone - Contact*					Email - Contact*			
Product-Env-Stew	ards	Product Enviro Compliance			NA	NA				Product-Env-Stewards@onsemi.com					
uthorized Repres	entative*	Title - Representative			Pho	Phone - Representative*				Email - Representative*					
Product-Env-Stewards			Product Enviro Compliance			NA	NA				Product-Env-Stewards@onsemi.com				
Request	ster Item Number Mfr Item		n Number Mfr Item Name			Eff	fective Dat	e Version		Manufacturing Site		Weight*	UOM	Unit Type	
		driver with			EN-LESS OPEN; Three phase insorless method (open loop		24-05-02			РНМ		80.0	mg	Each	
Ianufacturing	Process Information	n													
Terminal Plating / Grid Array Material To			Cerminal Base Alloy J-STD-020		STD-020 MSL Ratin	ıg	Peak Process Body Temperature		ure Max Time at Peak	Tempera	ture Numb	er of Reflow Cyc	cles		
contains Bi			CU Alloy 3				260 C 30			seconds 3					
omments															
TTENTION: MS	L 3 Rated item requires Ba	ake and D	ry Pack (after	electrical test)											
or more informat	ion regarding material con	nposition j	please refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier have not independently verified and or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	ial Weight Unit of Measure Level Substance		Substance	CAS	Exempt	Weight	Unit of Measure	
Die	3.9	mg	Supplier	Silicon (Si)	7440-21-3		3.8711	mg
			Supplier	Polyimide	Proprietary Data		0.0289	mg
Die Attach	0.5	mg	Supplier	Epoxized Condensate Of Para- Hydrobenzaldehyde And Alkyl Phenol	129915-35-1		0.1	mg
			Supplier	Silver (Ag)	7440-22-4		0.4	mg
Lead Frame	25.4	mg	Supplier	Silver (Ag)	7440-22-4		0.6325	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0483	mg
			Supplier	Iron (Fe)	7439-89-6		0.6426	mg
			Supplier	Copper (Cu)	7440-50-8		24.0411	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0356	mg
Mold Compound-Black	48.62	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		3.8896	mg
			Supplier	Epoxy Phenol Resin	Proprietary Data		1.3614	mg
			Supplier	Carbon Black (C)	1333-86-4		0.4862	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		1.4586	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		38.896	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		2.431	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		0.0972	mg
Plating	1.42	mg	В	Bismuth (Bi)	7440-69-9		0.0085	mg
			Supplier	Tin (Sn)	7440-31-5		1.4115	mg
Wire Bond - Au	0.16	mg	Supplier	Gold (Au)	7440-57-5		0.16	mg